



**Electrical Characteristics**

VCTL (L) =0V, VCTL (H) =3V, Pin=21.5dBm

(Ta=25 °C)

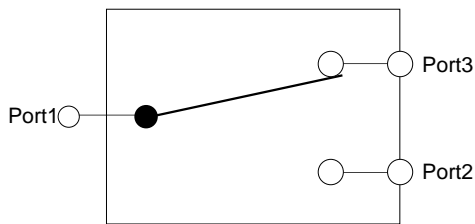
Item	Symbol	Condition	Min.	Typ.	Max.	Unit
Insertion loss	IL1	f=1.0 GHz		0.3	0.6	dB
Isolation	ISO1		30	35		dB
Insertion loss	IL2	f=2.0 GHz		0.5	0.8	dB
Isolation	ISO2		20	23		dB
Input VSWR	VSWRIN			1.3	1.5	
Output VSWR	VSWROUT			1.3	1.5	
Switching time	TSW			100		ns
Control pin current	ICTL			70	150	μA

VCTL (L) =0V, f =2.0GHz

(Ta=25 °C)

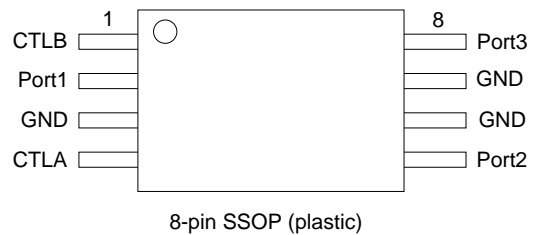
1 dB gain compression point output	P1dB (3)	VCTL (H) =3 V	26	29		dBm
1 dB gain compression point output	P1dB (4)	VCTL (H) =4 V	30	33		dBm

**Block Diagram**

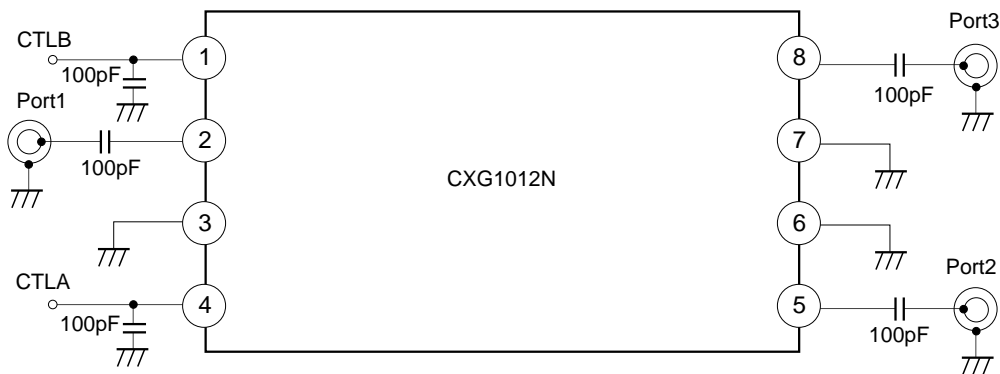


VCTLA	VCTLB	
High	Low	Port1-Port2 ON Port1-Port3 OFF
Low	High	Port1-Port2 OFF Port1-Port3 ON

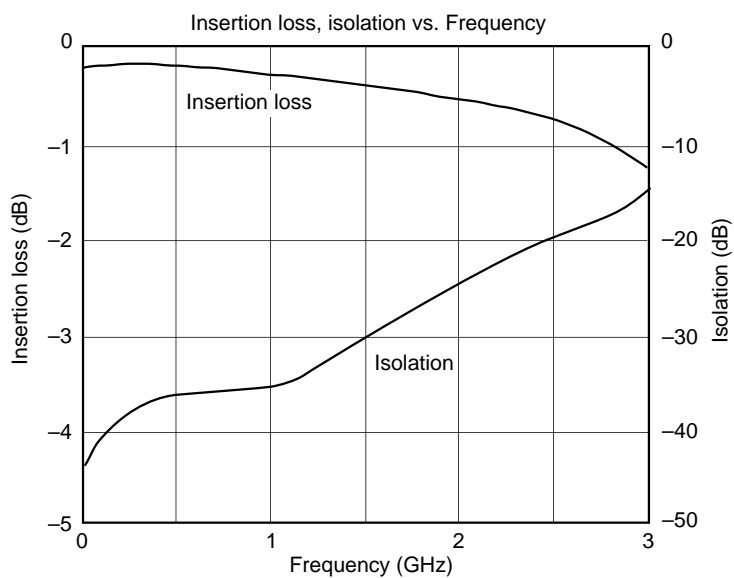
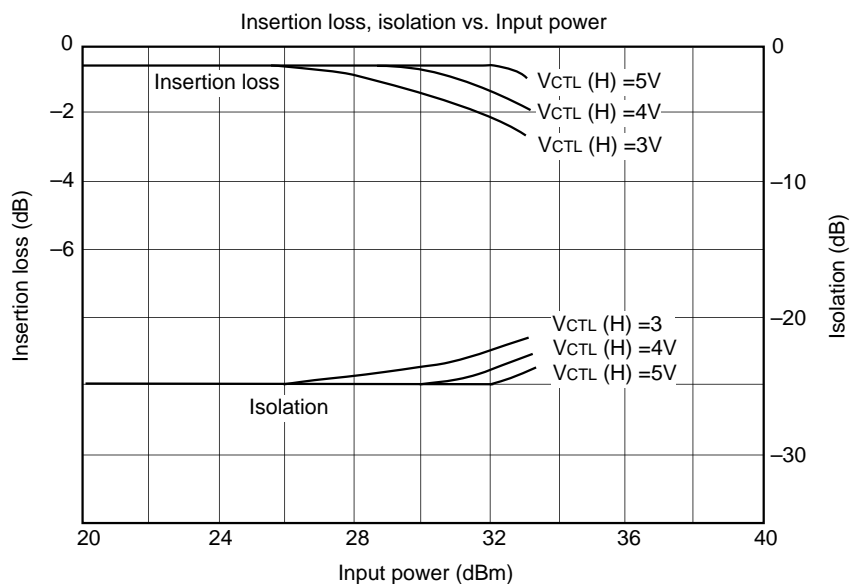
**Package outline/Pin Configuration**



Recommended Circuit

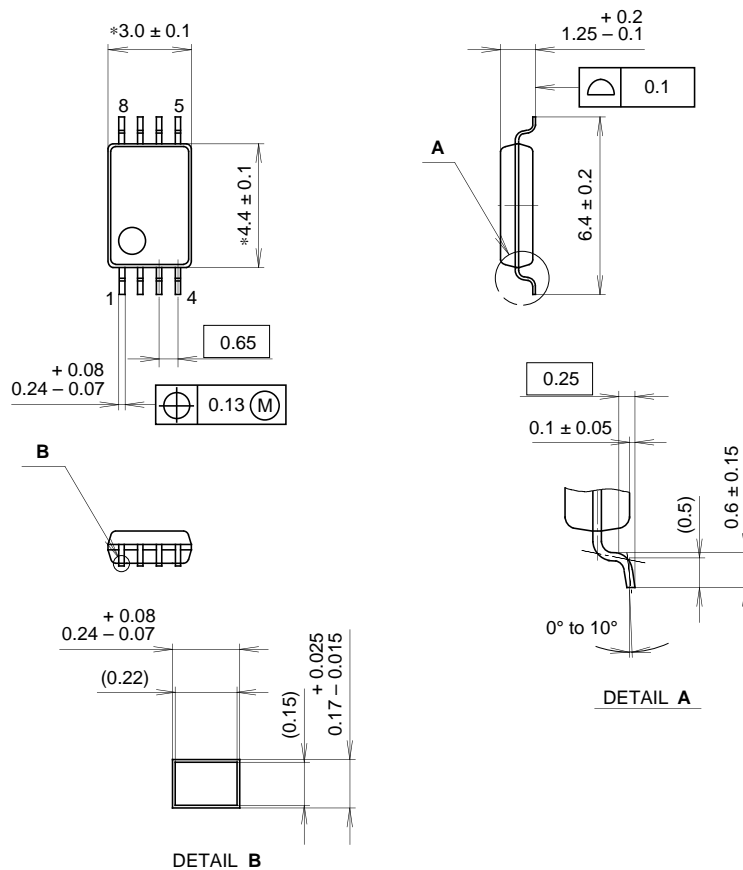


Example of Representative Characteristics (Ta=25 °C)



Package Outline Unit: mm

8PIN SSOP (PLASTIC)



NOTE: Dimension "\*" does not include mold protrusion.

PACKAGE STRUCTURE

SONY CODE	SSOP-8P-L01
EIAJ CODE	SSOP008-P-0044
JEDEC CODE	—

PACKAGE MATERIAL	EPOXY RESIN
LEAD TREATMENT	SOLDER / PALLADIUM PLATING
LEAD MATERIAL	COPPER ALLOY
PACKAGE WEIGHT	0.04g